ne<mark>x</mark>peria

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Should be replaced with:

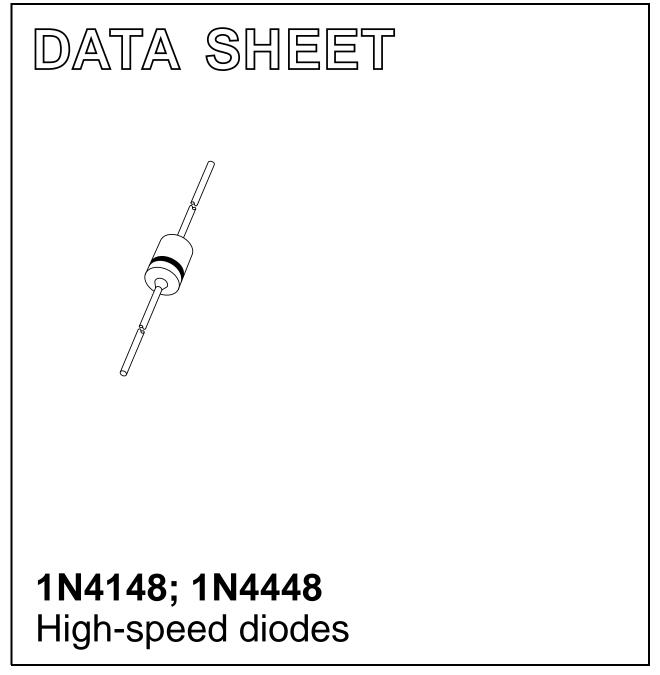
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Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 2002 Jan 23



1N4148; 1N4448

FEATURES

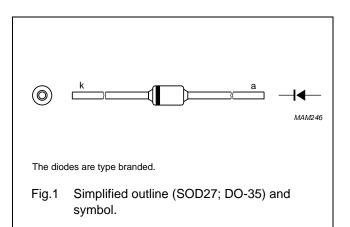
- Hermetically sealed leaded glass SOD27 (DO-35)
 package
- High switching speed: max. 4 ns
- General application
- Continuous reverse voltage: max. 100 V
- Repetitive peak reverse voltage: max. 100 V
- Repetitive peak forward current: max. 450 mA.

APPLICATIONS

• High-speed switching.

DESCRIPTION

The 1N4148 and 1N4448 are high-speed switching diodes fabricated in planar technology, and encapsulated in hermetically sealed leaded glass SOD27 (DO-35) packages.



MARKING

TYPE NUMBER	MARKING CODE
1N4148	1N4148PH or 4148PH
1N4448	1N4448

ORDERING INFORMATION

TYPE NUMBER		PACKAGE			
	NAME	DESCRIPTION	VERSION		
1N4148	-	hermetically sealed glass package; axial leaded; 2 leads	SOD27		
1N4448					

1N4148; 1N4448

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{RRM}	repetitive peak reverse voltage		-	100	V
V _R	continuous reverse voltage		-	100	V
I _F	continuous forward current	see Fig.2; note 1	-	200	mA
I _{FRM}	repetitive peak forward current		-	450	mA
I _{FSM}	non-repetitive peak forward current	square wave; T _j = 25 °C prior to surge; see Fig.4			
		t = 1 μs	_	4	А
		t = 1 ms	-	1	А
		t = 1 s	_	0.5	А
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	-	500	mW
T _{stg}	storage temperature		-65	+200	°C
Tj	junction temperature		-	200	°C

Note

1. Device mounted on an FR4 printed-circuit board; lead length 10 mm.

ELECTRICAL CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _F	forward voltage	see Fig.3			
	1N4148	I _F = 10 mA	-	1	V
	1N4448	I _F = 5 mA	0.62	0.72	V
		I _F = 100 mA	-	1	V
I _R	reverse current	$V_R = 20 V$; see Fig.5		25	nA
		V_R = 20 V; T _j = 150 °C; see Fig.5	-	50	μΑ
I _R	reverse current; 1N4448	V_R = 20 V; T_j = 100 °C; see Fig.5	-	3	μΑ
C _d	diode capacitance	$f = 1 MHz; V_R = 0 V; see Fig.6$	-	4	pF
t _{rr}	reverse recovery time	when switched from $I_F = 10$ mA to $I_R = 60$ mA; $R_L = 100 \Omega$; measured at $I_R = 1$ mA; see Fig.7	-	4	ns
V _{fr}	forward recovery voltage	when switched from $I_F = 50$ mA; $t_r = 20$ ns; see Fig.8	_	2.5	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-tp)}	thermal resistance from junction to tie-point	lead length 10 mm	240	K/W
R _{th(j-a)}	thermal resistance from junction to ambient	lead length 10 mm; note 1	350	K/W

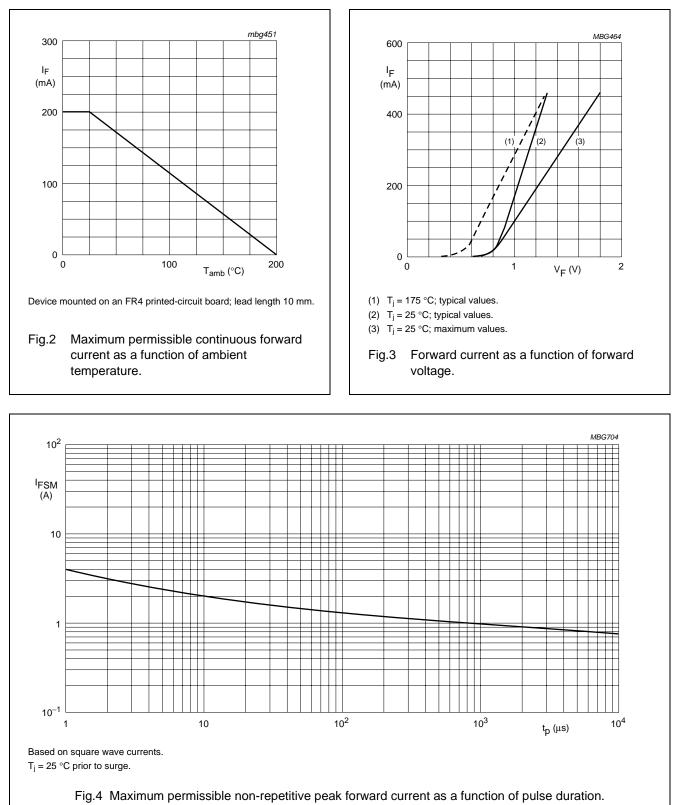
Note

Downloaded from Arrow.com.

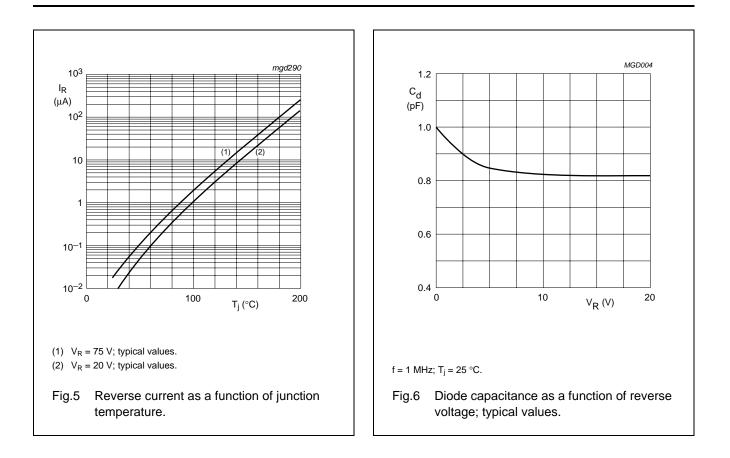
1. Device mounted on a printed-circuit board without metallization pad.

1N4148; 1N4448

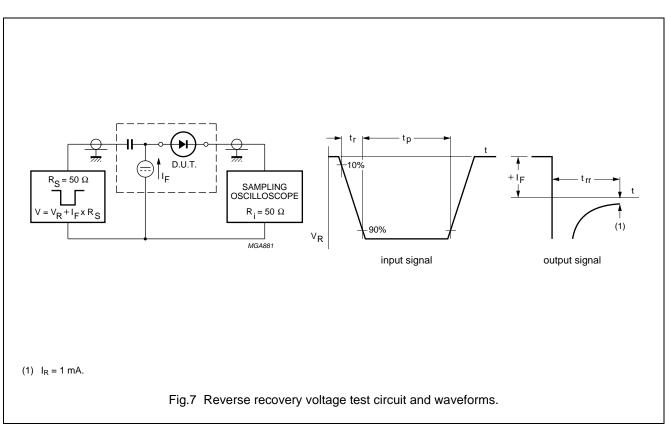
GRAPHICAL DATA

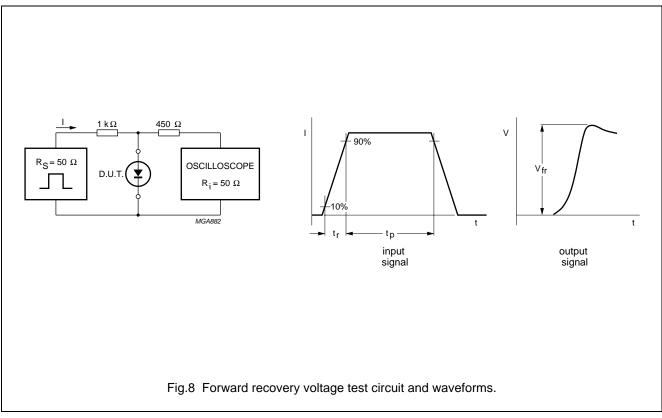


1N4148; 1N4448



1N4148; 1N4448





1N4148; 1N4448

PACKAGE OUTLINE

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1N4148; 1N4448

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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NXP Semiconductors

Customer notification

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Contact information

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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Printed in The Netherlands

R76/05/pp9

Date of release: 2004 Aug 10

Document order number: 9397 750 13541

